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Atty. Docket No.: 3449-0292P

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	2. Name and address of receiving party(ies) Name: LG ELECTRONICS INC. Internal Address: Street Address: 20, Yoido-dong, Youngdungpo-geo City: Seoul State: ZIP: Country: KOREA Postal Code: Additional name(s) & address(es) attached? YES NO		
If this document is being filed together with a new application, th A. Patent Application No(s). NEW	B. Patent No.(s).		
Additional numbers attac	hed? TYES NO		
Name and address of party to whom correspondence concerning document should be mailed: Name: BIRCH, STEWART, KOLASCH & BIRCH, LLP	6. Total No. of applications/patents involved: ONE (1) 7. Total fee (37 C.F.R. § 3.41): \$40.00 Enclosed		
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9. Statement and signature. James T. Eller, Jr., #39,538 Name of Person Signing/Reg. No.	June #41, 458 January 5, 2004 Signature Date		
Total number of pages including cover sheet, attachments, and document: Three (3)			
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PATENT REEL: 014877 FRAME: 0404

(Rev. 09/30/03)

BIRCH, STEWART, KOLASCH & BIRCH, LLP

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ASSIGNMENT

€ «	Application No. NEW		Filed January 5, 2004
Insert Name(s) of Inventor(s)	***(Given Name FAMILY NAME (ALL CAPS))***		
•	WHEREAS,	In Hwa JUNG	
		Jung Woo LEE	
		Sim Won CHIN	
•			
•	(hereinafter designated as the	undersigned) has (have) invented certain new a	nd useful improvements in
insert Title .			
of Invention	PIPING STRUCTURE OF AIR CONDITIONER		
		r Letters Patent of the United States of America of a provisional application),	rica has been executed by the
nsert Date	:		
of Signing of			
Application	on December 15, 2003		; and
nsert Name of Assignee	whereas, <u>lg e</u>	Electronics Inc.	
nsert Address	· :		
of Assignee	of 20, Yoido-dong, Yongd	lungpo-gu, Scoul, Korca	
	acquiring the entire right, title may be granted therefor in the	resentatives and assigns (hereinafter designated c and interest in and to said invention and in an e United States of America and	
F APPROPRIATE	in any forcign countries.		
. ' . ' . '	the receipt of which is hereby has (have) sold, assigned and	sideration of the sum of Ten Dollars (\$10.00) to y acknowledged, and other good and valuable d transferred, and by these presents does sell,	consideration, the undersigned assign and transfer unto said
	dependencies and possessions which may be granted therefor	ive right to the said invention in the United States and the entire right, title and interest in and to in the United States of America, its territories, nated, in any and all foreign countries;	o any and all Letters Patent(s)
	and to any and all divisions, reterms for which the same may	reissues, continuations, conversions and extensions to be granted.	ons thereof for the full term or

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PATENT REEL: 014877 FRAME: 0405 The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional, conversion or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree (s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation, division, conversion or reissue thereof or Letter Patent(s) or reissue patent issued thereon and to cooperate with the Assignee in every way possible in obtaining and producing evidence and proceeding with such interference.

The undersigned agree(s) to execute all papers and documents and to perform any act which may be necessary in connection with claims or provisions of the International Convention for the Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States of America patent(s) or a grant of a valid United States of America and any foreign patent(s) to the Assignee and to vest all rights therein hereby conveyed to said Assignee as fully and entirely as the same would have been held by the undersigned if this Assignment and sale had not been made.

The undersigned hereby authorize(s) and request(s) the Patent and Trademark Office Officials in the United States of America and in any foreign countries to issue any and all Letters Patents resulting from said application or any continuing, divisional conversion or reissue applications thereof to the said Assignce, as Assignee of the entire interest, and hereby covenants that he has (they have) the full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

The undersigned hereby grant(s) the law firm of Birch, Stewart, Kolasch & Birch, LLP the power to insert on this Assignment any further identification which may be necessary or desirable in order to comply with the rules of the U.S. Patent and Trademark Office for recordation of this document.

The undersigned hereby covenant(s) that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

Date	Dec. 11, 2003	Name of Inventor	J. W. Lee (signature) Jung Woo LEE
Date	Dec. 15, 2003	Name of Inventor	
Date	Dec. 15, 2003	Name of Inventor	TUTA
Date		Name of Inventor	(signature)
Date	,	Name of Inventor	(signature)

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RECORDED: 01/05/2004

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